

**DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I HEREBY DECLARE:

THAT my residence, post office address, and citizenship are as stated below next to my name;

THAT I believe I am the original, first, and sole inventor (if only one inventor is named below) or an original, first, and joint inventor (if plural inventors are named below or in an attached Declaration) of the subject matter which is claimed and for which a patent is sought on the invention entitled

Method of Forming Thin Film on Base Substance via Intermediate Layer

the specification of which (check one)

\_\_\_\_\_ is attached hereto.

  x   was filed on October 29, 2003 as United States Application  
Number or PCT International Application  
Number PCT/JP03/13887 and was amended  
on \_\_\_\_\_ (if applicable).

THAT I do not know and do not believe that the same invention was ever known or used by others in the United States of America, or was patented or described in any printed publication in any country, before I (we) invented it;

THAT I do not know and do not believe that the same invention was patented or described in any printed publication in any country, or in public use or on sale in the United States of America, for more than one year prior to the filing date of this United States application;

THAT I do not know and do not believe that the same invention was first patented or made the subject of an inventor's certificate that issued in any country foreign to the United States of America before the filing date of this United States application if the foreign application was filed by me (us), or by my (our) legal representatives or assigns, more than twelve months (six months for design patents) prior to the filing date of this United States application;

THAT I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment specifically referred to above;

THAT I believe that the above-identified specification contains a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise,

and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the invention, and sets forth the best mode contemplated by me of carrying out the invention; and

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Prior Foreign Application Number	Country	Foreign Filing Date	Priority Claimed?	Certified Copy Attached?
2002-318477(P)	Japan	October 31, 2002	yes	no

I HEREBY CLAIM the benefit under Title 35, United States Code § 119(e) of any United States provisional application(s) listed below.

U.S. Provisional Application Number	Filing Date

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I HEREBY APPOINT the registered attorneys and agents at Customer Number 22428

Customer Number: 22428

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I request that all correspondence be directed to:

David A. Blumenthal  
FOLEY & LARDNER LLP

Customer Number: 22428

Telephone: (202) 672-5407

Facsimile: (202) 672-5399

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1 - ∞ Name of first inventor

Katsuya HASEGAWA

Residence

Osaka-shi, Osaka, Japan JPX.

Citizenship

Japanese

Post Office Address

c/o Osaka Works of Sumitomo Electric Industries, Ltd.,  
1-3, Shimaya 1-chome, Konohana-ku, Osaka-shi,  
Osaka 554-8511 Japan

Inventor's signature

Katsuya Hasegawa

Date

November 17, 2004

Name of second inventor	Teruo IZUMI
Residence	Koto-ku, Tokyo, Japan
Citizenship	Japanese
Post Office Address	c/o Superconductivity Research Laboratory, International Superconductivity Technology Center, The Juridical Foundation, 10-13, Shinonome 1-chome, Koto-ku, Tokyo 135-0062 Japan
Inventor's signature	
Date	
Name of third inventor	Yuh SHIOHARA
Residence	Koto-ku, Tokyo, Japan
Citizenship	Japanese
Post Office Address	c/o Superconductivity Research Laboratory, International Superconductivity Technology Center, The Juridical Foundation, 10-13, Shinonome 1-chome, Koto-ku, Tokyo 135-0062 Japan
Inventor's signature	
Date	
Name of fourth inventor	Yoshihiro SUGAWARA
Residence	Nagoya-shi, Aichi, Japan
Citizenship	Japanese
Post Office Address	c/o Japan Fine Ceramics Center, 4-1, Mutsuno 2-chome, Atsuta-ku, Nagoya-shi, Aichi 456-8587 Japan
Inventor's signature	
Date	
Name of fifth inventor	Tsukasa HIRAYAMA
Residence	Nagoya-shi, Aichi, Japan
Citizenship	Japanese
Post Office Address	c/o Japan Fine Ceramics Center, 4-1, Mutsuno 2-chome, Atsuta-ku, Nagoya-shi, Aichi 456-8587 Japan
Inventor's signature	
Date	

Atty. Dkt. No. \_\_\_\_\_

Name of sixth inventor	Fumiyasu OBA
Residence	Kyoto-shi, Kyoto, Japan
Citizenship	Japanese
Post Office Address	<b>c/o Department of Materials Science and Engineering, Kyoto University, Yoshida-honmachi, Sakyo-ku , Kyoto-shi, Kyoto 606-8501 Japan</b>
Inventor's signature	
Date	

Name of seventh inventor	Yuichi IKUHARA
Residence	Bunkyo-ku, Tokyo, Japan
Citizenship	Japanese
Post Office Address	<b>c/o Institute of Engineering Innovation, The University of Tokyo, 2-11-16, Yayoi, Bunkyo-ku, Tokyo 113-8656 Japan</b>
Inventor's signature	
Date	

Name of eighth inventor	
Residence	
Citizenship	
Post Office Address	
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Residence	Osaka-shi, Osaka, Japan
Citizenship	Japanese
Post Office Address	c/o Osaka Works of Sumitomo Electric Industries, Ltd., 1-3, Shimaya 1-chome, Konohana-ku, Osaka-shi, Osaka 554-8511 Japan
Inventor's signature	
Date	



2 - ∞

Name of second inventor

Teruo IZUMI

Residence

Koto-ku, Tokyo, Japan JPX

Citizenship

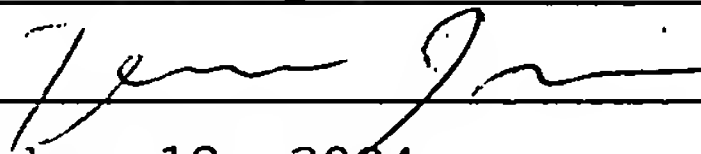
Japanese

Post Office Address

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International Superconductivity Technology Center, The  
Juridical Foundation, 10-13, Shinonome 1-chome, Koto-ku,  
Tokyo 135-0062 Japan

Inventor's signature

Date

  
November 18, 2004

3 - ∞

Name of third inventor

Yuh SHIOHARA

Residence

Koto-ku, Tokyo, Japan JPX

Citizenship

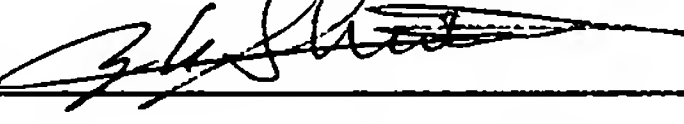
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Juridical Foundation, 10-13, Shinonome 1-chome, Koto-ku,  
Tokyo 135-0062 Japan

Inventor's signature

Date

  
November 18, 2004

Name of fourth inventor

Yoshihiro SUGAWARA

Residence

Nagoya-shi, Aichi, Japan

Citizenship

Japanese

Post Office Address

c/o Japan Fine Ceramics Center, 4-1, Mutsuno 2-chome,  
Atsuta-ku, Nagoya-shi, Aichi 456-8587 Japan

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Date

Name of fifth inventor

Tsukasa HIRAYAMA

Residence

Nagoya-shi, Aichi, Japan

Citizenship

Japanese

Post Office Address

c/o Japan Fine Ceramics Center, 4-1, Mutsuno 2-chome,  
Atsuta-ku, Nagoya-shi, Aichi 456-8587 Japan

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Date

Name of sixth inventor	Fumiyasu OBA
Residence	Kyoto-shi, Kyoto, Japan
Citizenship	Japanese
Post Office Address	c/o Department of Materials Science and Engineering, Kyoto University, Yoshida-honmachi, Sakyo-ku , Kyoto-shi, Kyoto 606-8501 Japan
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Name of seventh inventor	Yuichi IKUHARA
Residence	Bunkyo-ku, Tokyo, Japan
Citizenship	Japanese
Post Office Address	c/o Institute of Engineering Innovation, The University of Tokyo, 2-11-16, Yayoi, Bunkyo-ku, Tokyo 113-8656 Japan
Inventor's signature	
Date	

Name of eighth inventor	
Residence	
Citizenship	
Post Office Address	
Inventor's signature	
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Atty. Dkt. No: \_\_\_\_\_

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 Residence Koto-ku, Tokyo, Japan  
 Citizenship Japanese  
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 Juridical Foundation, 10-13, Shinonome 1-chome, Koto-ku,  
 Tokyo 135-0062 Japan  
 Inventor's signature \_\_\_\_\_  
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Name of third inventor Yuh SHIOHARA  
 Residence Koto-ku, Tokyo, Japan  
 Citizenship Japanese  
 Post Office Address c/o Superconductivity Research Laboratory,  
 International Superconductivity Technology Center, The  
 Juridical Foundation, 10-13, Shinonome 1-chome, Koto-ku,  
 Tokyo 135-0062 Japan  
 Inventor's signature \_\_\_\_\_  
 Date \_\_\_\_\_

4-8 Name of fourth inventor Yoshihiro SUGAWARA  
 Residence Nagoya-shi, Aichi, Japan JPX  
 Citizenship Japanese  
 Post Office Address c/o Japan Fine Ceramics Center, 4-1, Mutsuno 2-chome,  
 Atsuta-ku, Nagoya-shi, Aichi 456-8587 Japan  
 Inventor's signature Yoshihiro Sugawara  
 Date November 16, 2004

5-8 Name of fifth inventor Tsukasa HIRAYAMA  
 Residence Nagoya-shi, Aichi, Japan JPX  
 Citizenship Japanese  
 Post Office Address c/o Japan Fine Ceramics Center, 4-1, Mutsuno 2-chome,  
 Atsuta-ku, Nagoya-shi, Aichi 456-8587 Japan  
 Inventor's signature Tsukasa Hirayama  
 Date November 16, 2004



Name of sixth inventor	Fumiyasu OBA
Residence	Kyoto-shi, Kyoto, Japan
Citizenship	Japanese
Post Office Address	<b>c/o Department of Materials Science and Engineering, Kyoto University, Yoshida-honmachi, Sakyo-ku , Kyoto-shi, Kyoto 606-8501 Japan</b>
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Name of seventh inventor	Yuichi IKUHARA
Residence	Bunkyo-ku, Tokyo, Japan
Citizenship	Japanese
Post Office Address	<b>c/o Institute of Engineering Innovation, The University of Tokyo, 2-11-16, Yayoi, Bunkyo-ku, Tokyo 113-8656 Japan</b>
Inventor's signature	
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Name of eighth inventor	
Residence	
Citizenship	
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6 - ∞ Name of sixth inventor

Fumiyasu OBA

Residence

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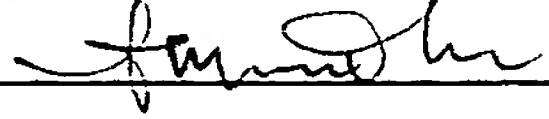
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Date

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Name of seventh inventor

Yuichi IKUHARA

Residence

Bunkyo-ku, Tokyo, Japan

Citizenship

Japanese

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Inventor's signature

Date

Name of eighth inventor

Residence

Citizenship

Post Office Address

Inventor's signature

Date



**DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I HEREBY DECLARE:

THAT my residence, post office address, and citizenship are as stated below next to my name;

THAT I believe I am the original, first, and sole inventor (if only one inventor is named below) or an original, first, and joint inventor (if plural inventors are named below or in an attached Declaration) of the subject matter which is claimed and for which a patent is sought on the invention entitled

Method of Forming Thin Film on Base Substance via Intermediate Layer

the specification of which (check one)

\_\_\_\_\_ is attached hereto.

  x   was filed on October 29, 2003 as United States Application  
Number or PCT International Application  
Number PCT/JP03/13887 and was amended  
on \_\_\_\_\_ (if applicable).

THAT I do not know and do not believe that the same invention was ever known or used by others in the United States of America, or was patented or described in any printed publication in any country, before I (we) invented it;

THAT I do not know and do not believe that the same invention was patented or described in any printed publication in any country, or in public use or on sale in the United States of America, for more than one year prior to the filing date of this United States application;

THAT I do not know and do not believe that the same invention was first patented or made the subject of an inventor's certificate that issued in any country foreign to the United States of America before the filing date of this United States application if the foreign application was filed by me (us), or by my (our) legal representatives or assigns, more than twelve months (six months for design patents) prior to the filing date of this United States application;

THAT I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment specifically referred to above;

THAT I believe that the above-identified specification contains a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise,

and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the invention, and sets forth the best mode contemplated by me of carrying out the invention; and

THAT I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I HEREBY CLAIM foreign priority benefits under Title 35, United States Code §119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or §365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below any foreign application for patent or inventor's certificate or of any PCT international application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application Number	Country	Foreign Filing Date	Priority Claimed?	Certified Copy Attached?
2002-318477(P)	Japan	October 31, 2002	yes	no

I HEREBY CLAIM the benefit under Title 35, United States Code § 119(e) of any United States provisional application(s) listed below.

U.S. Provisional Application Number	Filing Date

I HEREBY CLAIM the benefit under Title 35, United States Code, §120 of any United States application(s), or § 365(c) of any PCT international application designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

U.S. Parent Application Number	PCT Parent Application Number	Parent Filing Date	Parent Patent Number

I HEREBY APPOINT the registered attorneys and agents at Customer Number 22428

### Customer Number: 22428

to have full power to prosecute this application and any continuations, divisions, reissues, and reexaminations thereof, to receive the patent, and to transact all business in the United States Patent and Trademark Office connected therewith.

I request that all correspondence be directed to:

David A. Blumenthal  
FOLEY & LARDNER LLP  
Customer Number: 22428

Telephone: (202) 672-5407  
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I UNDERSTAND AND AGREE THAT the foregoing attorneys and agents appointed by me to prosecute this application do not personally represent me or my legal interests, but instead represent the interests of the legal owner(s) of the invention described in this application.

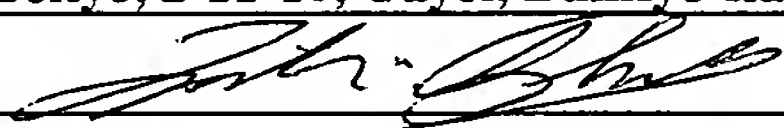
I FURTHER DECLARE THAT all statements made herein of my own knowledge are true, and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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Name of seventh inventor	<u>Yuichi IKUHARA</u>
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Inventor's signature	
Date	Nov. 16, 2004

Name of eighth inventor	
Residence	
Citizenship	
Post Office Address	
Inventor's signature	
Date	